General Description

The SJP40N058 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

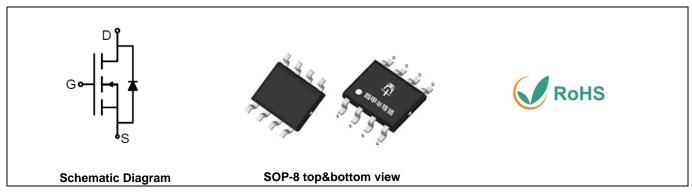
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	40	V
R _{DS(ON)_TYP}	7.4	mΩ
I _D	14	A
Q _G	41	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJP40N058	SJP40N058	SOP-8	Tape	\	\	4000 Pcs

Table 1. Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	40	V
V _G S	Gate-Source Voltage (V _{DS} =0V)	±20	V
1	Drain Current-Continuous(T _A =25°C)		А
I _D	Drain Current-Continuous(T _A =100°C)	8.7	А
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	56	А
D-	Maximum Power Dissipation(T _A =25°C)	3.3	W
P _D	Maximum Power Dissipation(T _A =100°C)	1.3	W
Eas	Avalanche energy (Note 2)	132	mJ
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{ heta JA}$	R _{θJA} Thermal Resistance, Junction-to-Ambient		37.4	°C/W



Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	40			V
	7 0 1 1/1 2 1 0 1	V _{DS} =40V, V _{GS} =0V T _J =25°C			1	μA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V T _J =125°C			100	μA
Igss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1		2.5	V
g FS	Forward Transconductance	V _{DS} =10V, I _D =20A		38.8		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A T _J =25°C		7.4	9.3	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =15A T _J =25°C		8.7	11.6	mΩ
Dynamic Chara	acteristics		Į.	I	I.	
Ciss	Input Capacitance			2181		pF
C_{oss}	Output Capacitance	V _{DS} =20V,V _{GS} =0V, f=1.0MHz		165		pF
Crss	Reverse Transfer Capacitance			134		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		2.43		Ω
Switching Para	meters		Į.	I	I.	
t _{d(on)}	Turn-on Delay Time			8.4		nS
t _r	Turn-on Rise Time	V _{GS} =10V, V _{DS} =20V,		6.2		nS
t _{d(off)}	Turn-Off Delay Time	$R_L=1\Omega$, $R_{GEN}=3\Omega$		40.2		nS
t _f	Turn-Off Fall Time			7.8		nS
Q_g	Total Gate Charge			41		nC
Q _{gs}	Gate-Source Charge	V _{GS} =10V, V _{DS} =20V, I _D =20A		5.5		nC
Q_{gd}	Gate-Drain Charge			8.0		nC
Source-Drain D	Diode Characteristics		I.	I	I.	
I _{SD}	Source-Drain Current (Body Diode)				14	Α
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI/dt=100A/μs		18.3		ns
Qrr	Reverse Recovery Charge	I _F =20A, dI/dt=100A/μs		12.8		nC
			1	1	1	

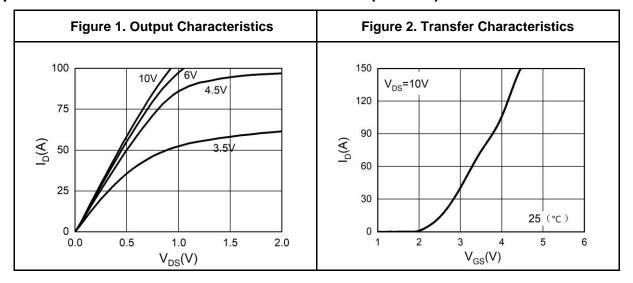
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

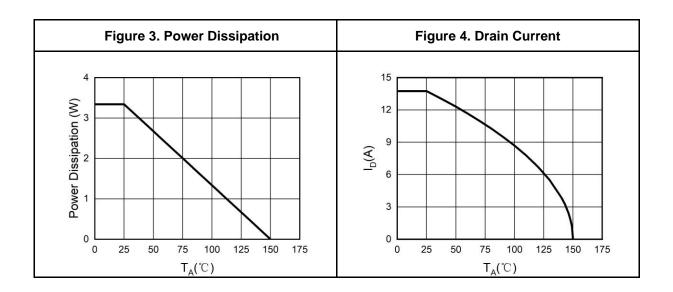
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=40V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

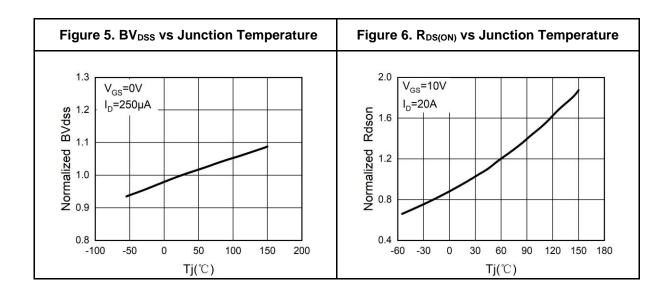
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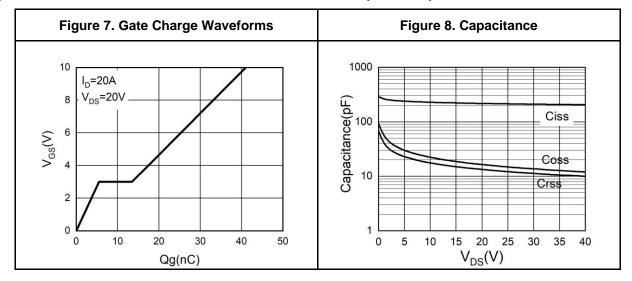
Typical Electrical And Thermal Characteristics (Curves)

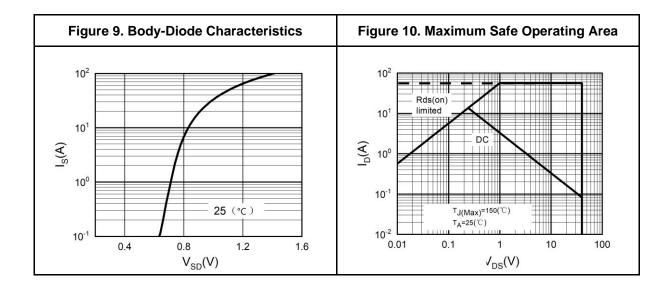






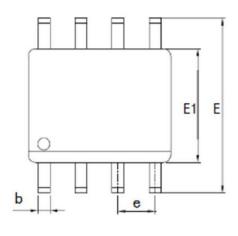
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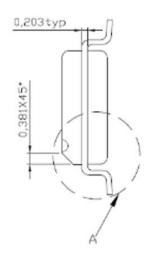


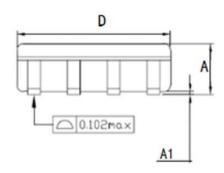


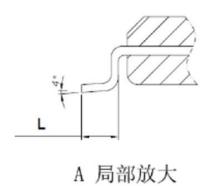


SOP-8 Package Information









	Dime			
Symbol	Min.	Nom.	Max	
A	1.35	1.55	1.75	
A1	0.1	0.15	0.2	
b	0.346	0.406	0.466	
D	4.8	4.89	4.98	
E	5.75	6.00	6.25	
E1	3.81	3.90	3.99	
е	1.27TYP			
L	0.406	0.838	1.27	

Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

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